

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Matthew V. Kaufmann</td> <td>04/16/2007</td> </tr> <tr> <td>Teck Yang Tan</td> <td>04/24/2007</td> </tr> </tbody> </table>		Name	Execution Date	Matthew V. Kaufmann	04/16/2007	Teck Yang Tan	04/24/2007
Name	Execution Date						
Matthew V. Kaufmann	04/16/2007						
Teck Yang Tan	04/24/2007						
RECEIVING PARTY DATA							
Name:	Broadcom Corporation						
Street Address:	5300 California Avenue						
City:	Irvine						
State/Country:	CALIFORNIA						
Postal Code:	92617						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11741804</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11741804		
Property Type	Number						
Application Number:	11741804						
CORRESPONDENCE DATA							
Fax Number:	(202)244-3088						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
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Correspondent Name:	Jeffrey S. Weaver						
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ATTORNEY DOCKET NUMBER:	A05.00110000						
NAME OF SUBMITTER:	Jeffrey S. Weaver						
Total Attachments: 4 source=Assignment1#page1.tif source=Assignment1#page2.tif source=Assignment2#page1.tif source=Assignment2#page2.tif							

OP \$40.00 11741804

ASSIGNMENT

In consideration of the sum of one dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned inventors: Matthew V. Kaufmann and Teck Yang Tan, hereby sells and assigns to Broadcom Corporation, a corporation formed under the laws of California, whose mailing address is 5300 California Avenue, Irvine, California 92617-3038 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present, and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

(a) in the invention(s) known as Highly Reliable Low Cost Structure for Wafer-Level Ball Grid Array Packaging for which application(s) for patent in the United States of America has a filing date or a 371(c) date of herewith, (also known as United States Application No. to be assigned) (Attorney Docket No. A05.00110000), in any and all applications thereon, in any and all Letters Patent(s) therefore, and

(b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefore listed above in part (a), to the full extent of the term or terms for which Letters Patent issue, and

(c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual property protection derivable from such patent application, and that are derivable from any and all continuing patent applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefore; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

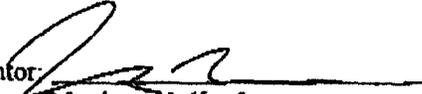
Appl. No. to be assigned
Docket No. A05.00110000

The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with **CUSTOMER NUMBER 68365** the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date: 4/16/07 Signature of Inventor: 
Matthew V. Kaufmann

Date: _____ Signature of Inventor: _____
Teck Yang Tan

ASSIGNMENT

In consideration of the sum of one dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned inventors: Matthew V. Kaufmann and Teck Yang Tan, hereby sells and assigns to Broadcom Corporation, a corporation formed under the laws of California, whose mailing address is 5300 California Avenue, Irvine, California 92617-3038 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present, and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

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(b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefore listed above in part (a), to the full extent of the term or terms for which Letters Patent issue, and

(c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual property protection derivable from such patent application, and that are derivable from any and all continuing patent applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefore; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

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IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date: _____ Signature of Inventor: _____
Matthew V. Kaufmann
Date: 24th April 2007 Signature of Inventor: 
Teck Yang Tan